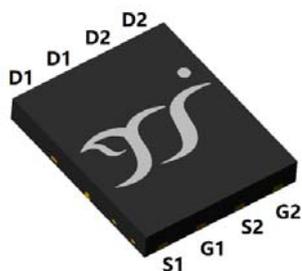
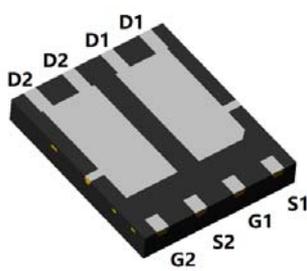


## N-Channel and P-Channel Complementary MOSFET

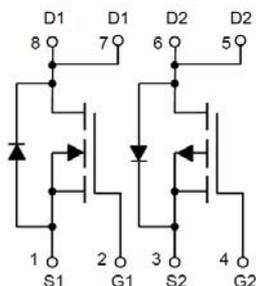


Top View



Bottom View

DFN5060-8L



### Product Summary

#### NMOS

- $V_{DS}$  100V
- $I_D$  10A
- $R_{DS(ON)}$  (at  $V_{GS}=10V$ )  $< 110\ m\Omega$
- $R_{DS(ON)}$  (at  $V_{GS}=4.5V$ )  $< 120\ m\Omega$

#### PMOS

- $V_{DS}$  -100V
- $I_D$  -18A
- $R_{DS(ON)}$  (at  $V_{GS}=-10V$ )  $< 110\ m\Omega$
- $R_{DS(ON)}$  (at  $V_{GS}=-4.5V$ )  $< 120\ m\Omega$
- 100% EAS Tested

### General Description

- Trench Power LV MOSFET technology
- Excellent package for heat dissipation
- Moisture Sensitivity Level 3
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

### Applications

- Load switching
- Hard switched and high frequency circuits
- Uninterruptible power supply

### ■ Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	NMOS	PMOS	Unit
Drain-source Voltage		$V_{DS}$	100	-100	V
Gate-source Voltage		$V_{GS}$	$\pm 20$	$\pm 20$	V
Drain Current	$T_A=25^\circ C$	$I_D$	2.5	-3	A
	$T_A=100^\circ C$		1.6	-1.9	
	$T_C=25^\circ C$		10	-18	
	$T_C=100^\circ C$		6.3	-12	
Pulsed Drain Current <sup>A</sup>		$I_{DM}$	40	-72	A
Avalanche energy <sup>B</sup>		EAS	6.25	30.25	mJ
Total Power Dissipation <sup>C</sup>	$T_A=25^\circ C$	$P_D$	2	2.5	W
	$T_A=100^\circ C$		0.8	1	
	$T_C=25^\circ C$		30	72	
	$T_C=100^\circ C$		12.5	29	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~+150	-55~+150	$^\circ C$

### ■ Thermal resistance

Parameter		Symbol	NMOS		PMOS		Units
			Typ	Max	Typ	Max	
Thermal Resistance Junction-to-Ambient <sup>D</sup>	Steady-State	$R_{\theta JA}$	50	60	40	50	$^\circ C/W$
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	3.2	4	1.35	1.7	



# YJG10NP10A

## ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJG10NP10A	F1	YJG10NP10A	5000	10000	100000	13" reel

## ■ NMOS Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V	-	-	1	μA
		V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, T <sub>J</sub> =150°C	-	-	100	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.1	1.8	3	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	-	90	110	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A	-	95	120	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =10A, V <sub>GS</sub> =0V	-	0.9	1.2	V
Gate resistance	R <sub>G</sub>	f=1MHz, Open drain	-	1.6	-	Ω
Maximum Body-Diode Continuous Current	I <sub>S</sub>		-	-	10	A
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f=1MHz	-	900	-	pF
Output Capacitance	C <sub>oss</sub>		-	35	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	30	-	
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =50V, I <sub>D</sub> =5A	-	16	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	2.5	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	2.6	-	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =5A, di/dt=350A/μs	-	90	-	nC
Reverse Recovery Time	t <sub>rr</sub>		-	35	-	ns
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =10V, V <sub>DD</sub> =50V, I <sub>D</sub> =5A R <sub>GEN</sub> =2.2Ω	-	5	-	ns
Turn-on Rise Time	t <sub>r</sub>		-	40	-	
Turn-off Delay Time	t <sub>D(off)</sub>		-	20	-	
Turn-off fall Time	t <sub>f</sub>		-	7	-	



# YJG10NP10A

## ■ PMOS Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =-250μA	-100	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V	-	-	-1	μA
		V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V, T <sub>J</sub> =150°C	-	-	-100	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1	-1.8	-2.5	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-10A	-	88	110	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-5A	-	95	120	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-10A, V <sub>GS</sub> =0V	-	-0.9	-1.3	V
Gate resistance	R <sub>G</sub>	f=1MHz, Open drain	-	10	-	Ω
Maximum Body-Diode Continuous Current	I <sub>S</sub>		-	-	-18	A
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-50V, V <sub>GS</sub> =0V, f=1MHz	-	1050	-	pF
Output Capacitance	C <sub>oss</sub>		-	120	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	25	-	
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-50V, I <sub>D</sub> =-5A	-	20	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	4	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	4.5	-	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =-5A, di/dt=100A/us	-	140	-	nC
Reverse Recovery Time	t <sub>rr</sub>		-	70	-	ns
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =-10V, V <sub>DD</sub> =-50V, R <sub>L</sub> =2.5Ω R <sub>GEN</sub> =6Ω	-	10	-	ns
Turn-on Rise Time	t <sub>r</sub>		-	30	-	
Turn-off Delay Time	t <sub>D(off)</sub>		-	77	-	
Turn-off fall Time	t <sub>f</sub>		-	81	-	

A. Repetitive rating; pulse width limited by max. junction temperature.

B. NMOS: T<sub>J</sub>=25°C, V<sub>DD</sub>=50V, V<sub>G</sub>=10V, R<sub>G</sub>=25Ω, L=0.5mH, I<sub>AS</sub>=5A.

PMOS: T<sub>J</sub>=25°C, V<sub>DD</sub>=-50V, V<sub>G</sub>=-10V, R<sub>G</sub>=25Ω, L=0.5mH, I<sub>AS</sub>=-11A.

C. P<sub>d</sub> is based on max. junction temperature, using junction-case thermal resistance.

D. The value of R<sub>θJA</sub> is measured with the device mounted on the minimum recommend pad size, in the still air environment with T<sub>A</sub>=25°C. The maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.



# YJG10NP10A

## ■ NMOS Typical Electrical and Thermal Characteristics Diagrams

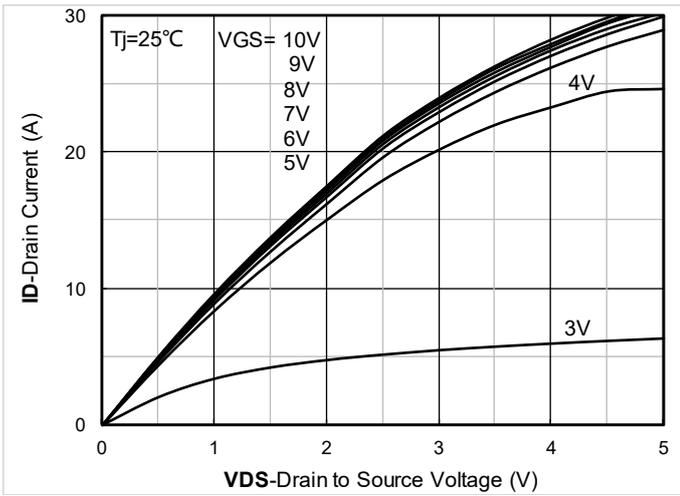


Figure1. Output Characteristics

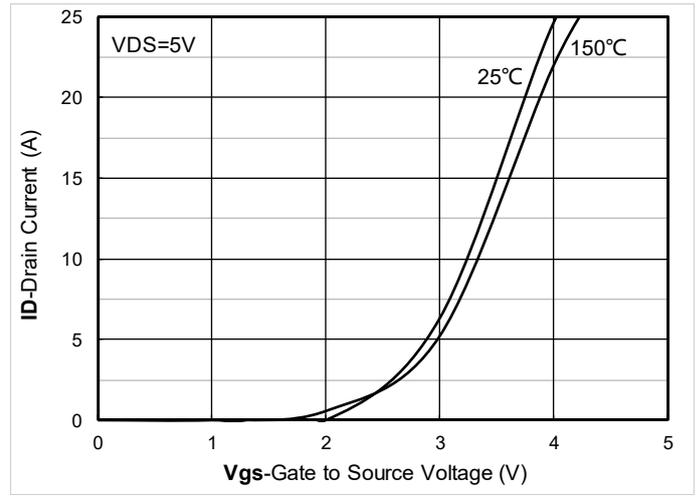


Figure2. Transfer Characteristics

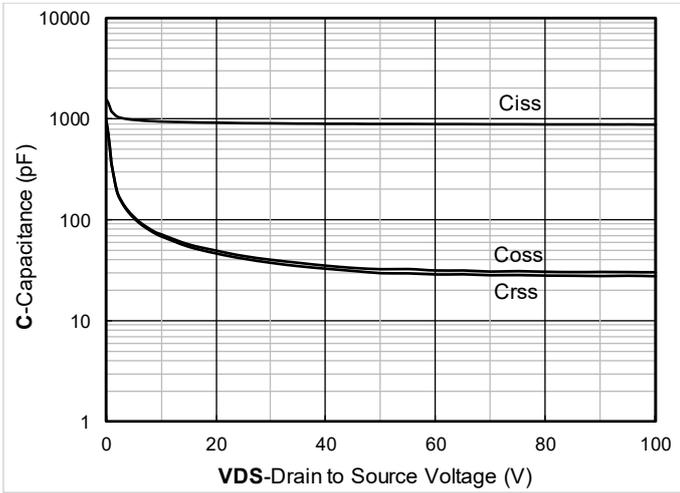


Figure3. Capacitance Characteristics

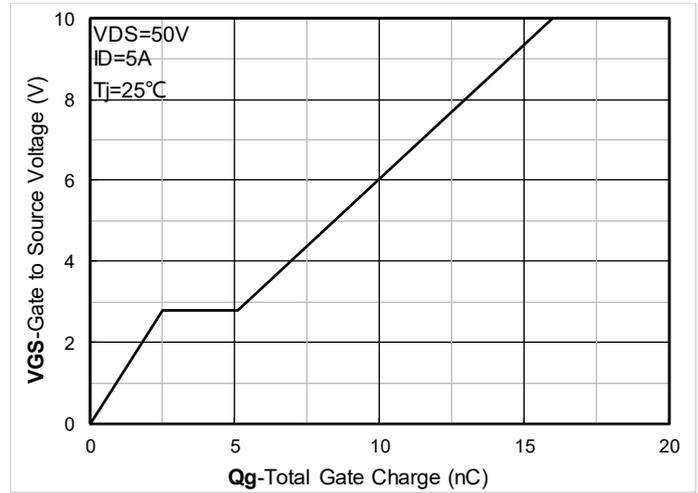


Figure4. Gate Charge

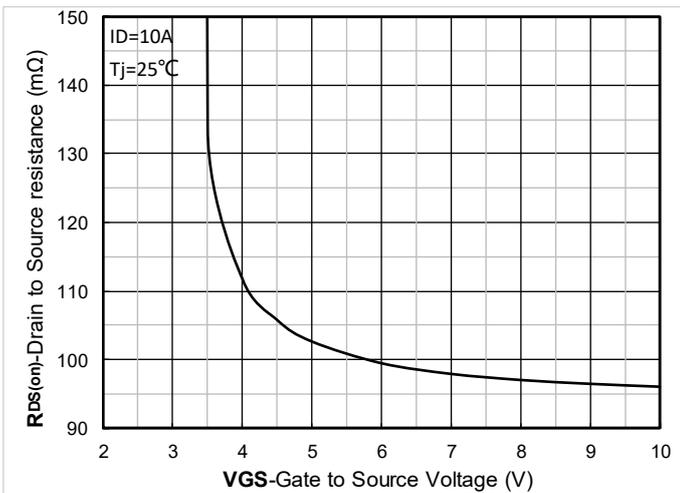


Figure5. On-Resistance vs Gate to Source Voltage

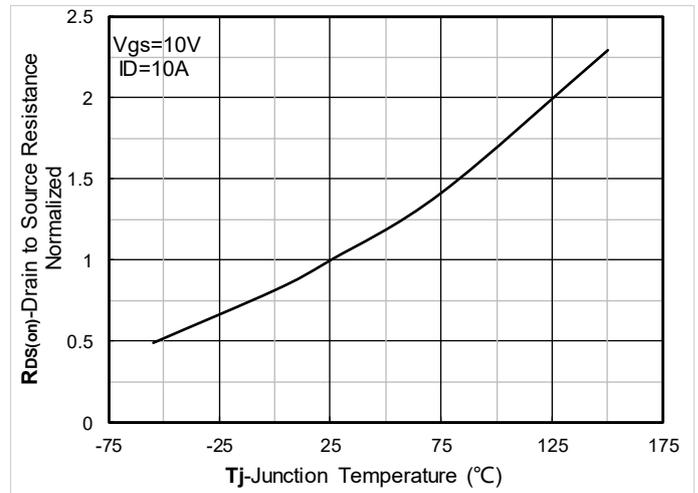


Figure6. Normalized On-Resistan



# YJG10NP10A

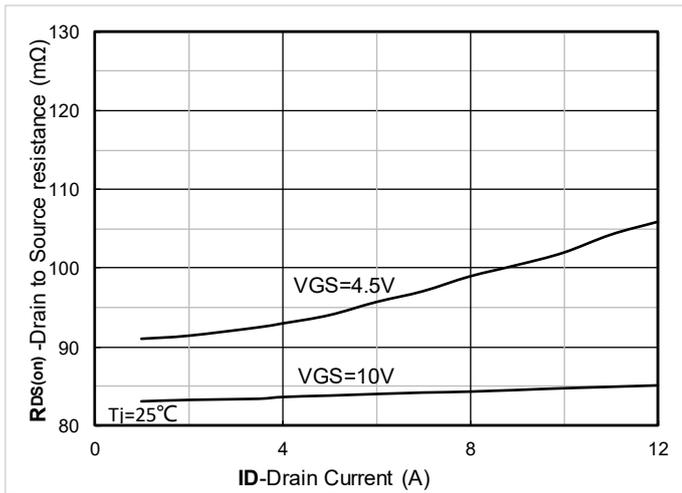


Figure 7.  $R_{DS(on)}$  VS Drain Current

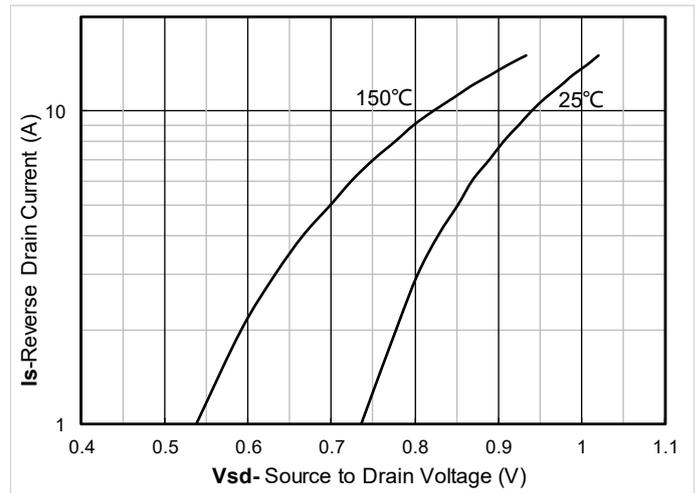


Figure 8. Forward characteristics of reverse diode

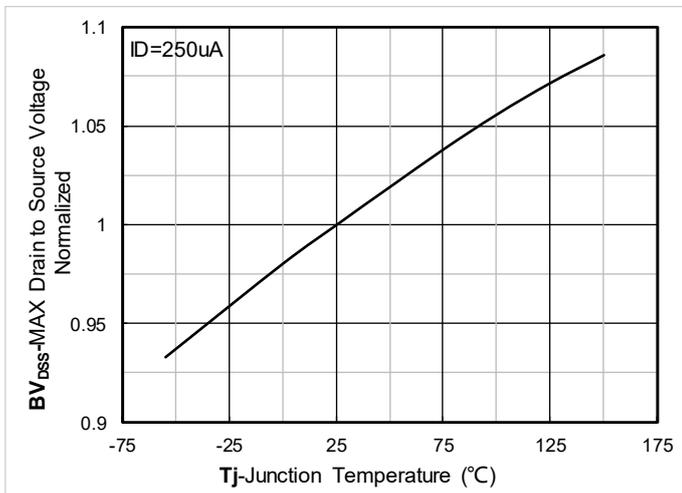


Figure 9. Normalized breakdown voltage

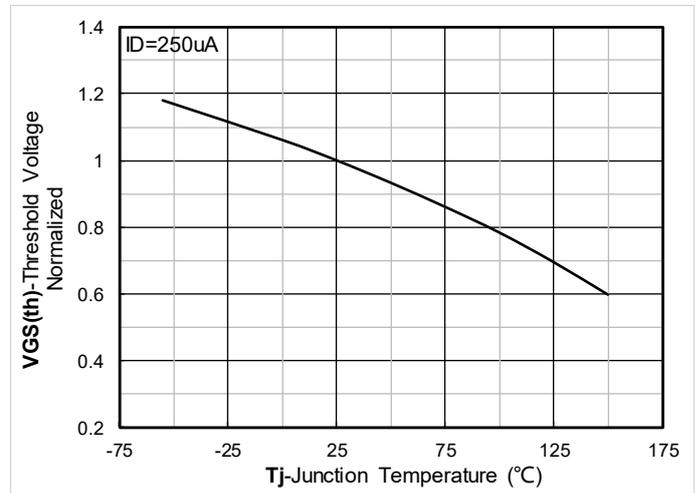


Figure 10. Normalized Threshold voltage

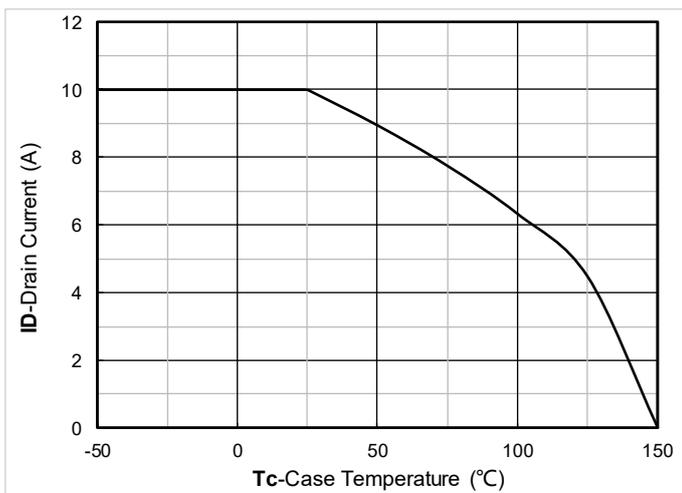


Figure 11. Current dissipation

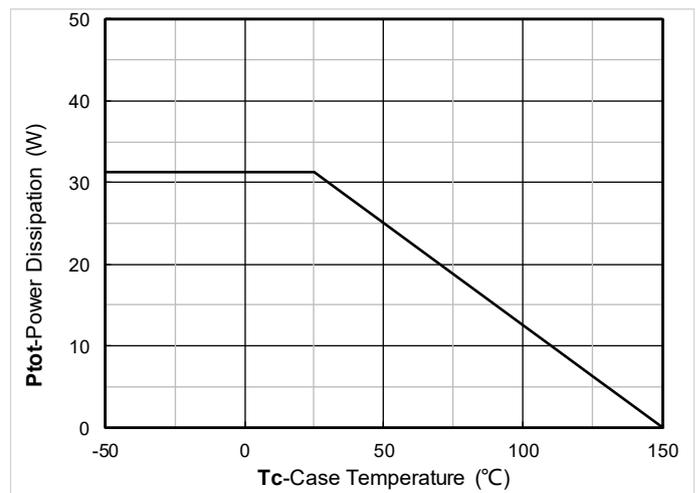


Figure 12. Power dissipation



# YJG10NP10A

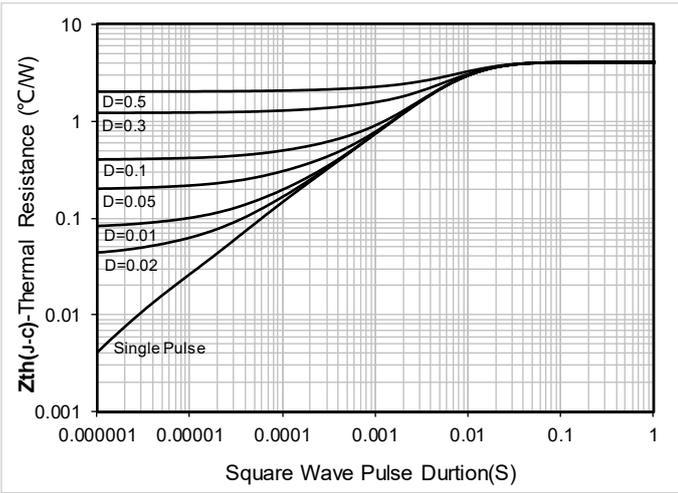


Figure13. Maximum Transient Thermal Impedance

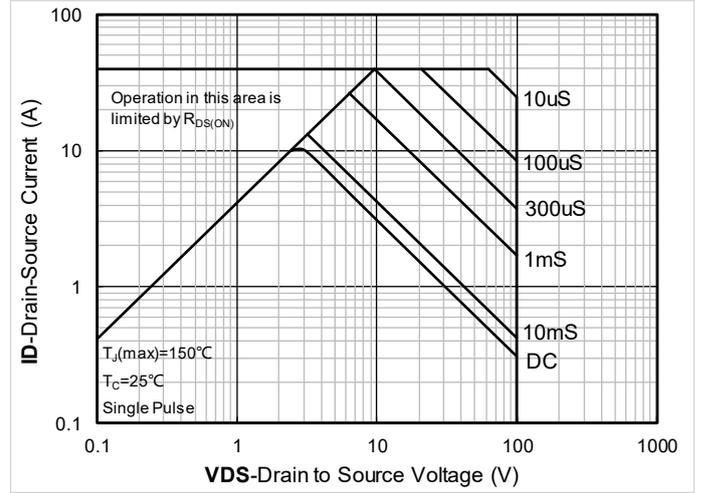


Figure14. Safe Operation Area

## PMOS Typical Electrical and Thermal Characteristics Diagrams

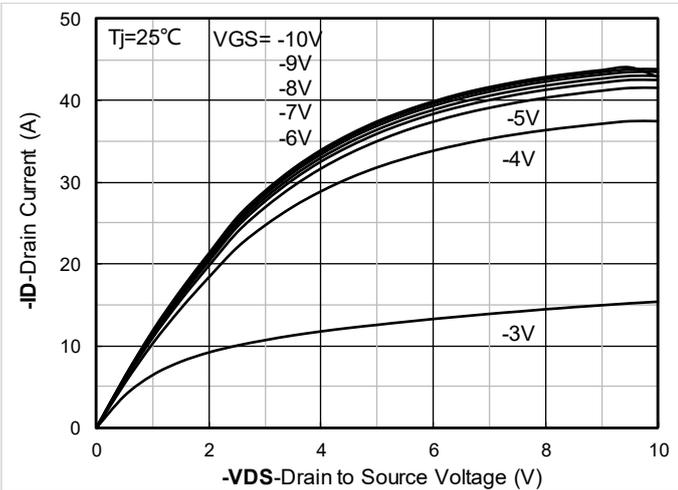


Figure1. Output Characteristics

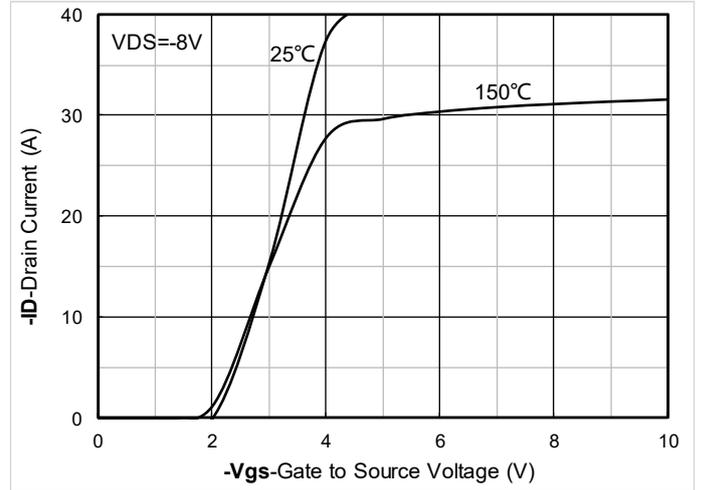


Figure2. Transfer Characteristics

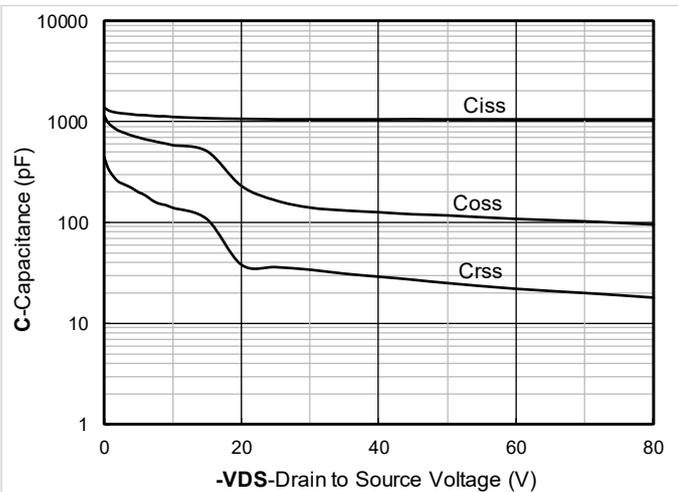


Figure3. Capacitance Characteristics

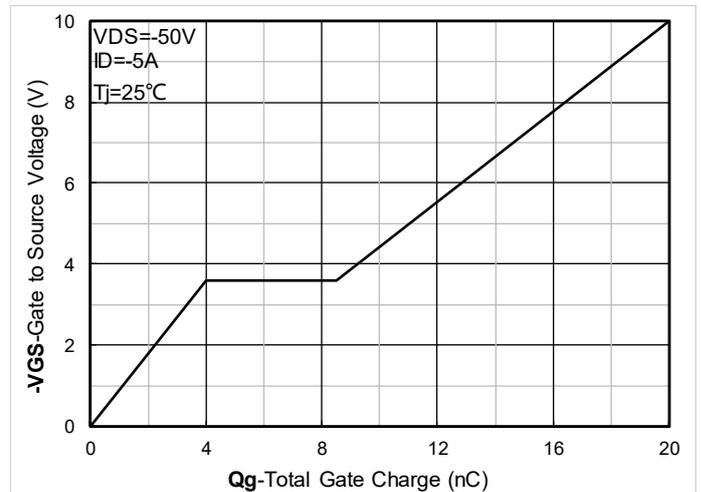


Figure4. Gate Charge



# YJG10NP10A

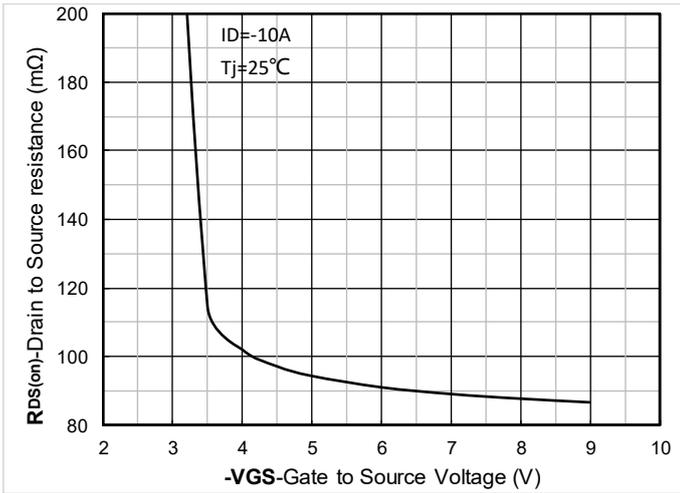


Figure5. On-Resistance vs Gate to Source Voltage

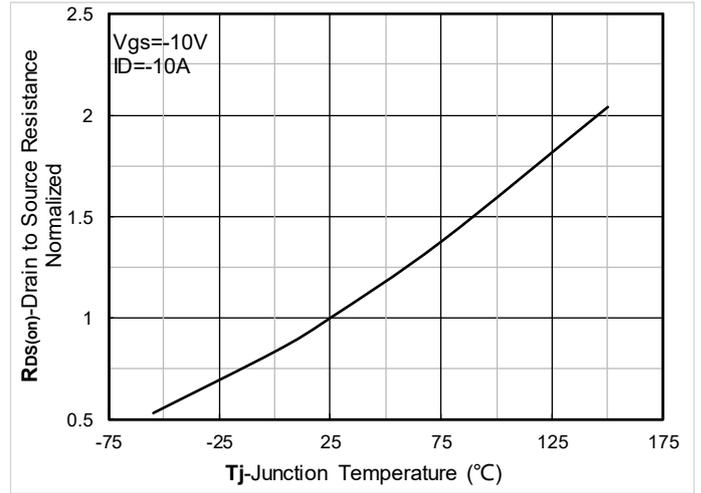


Figure6. Normalized On-Resistance

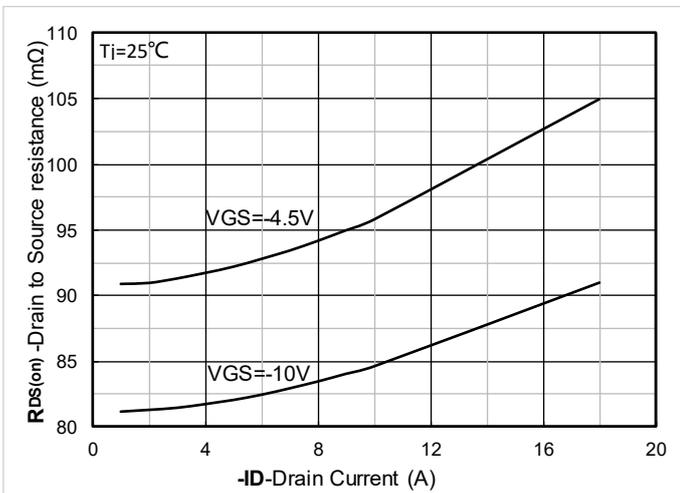


Figure7. RDS(on) VS Drain Current

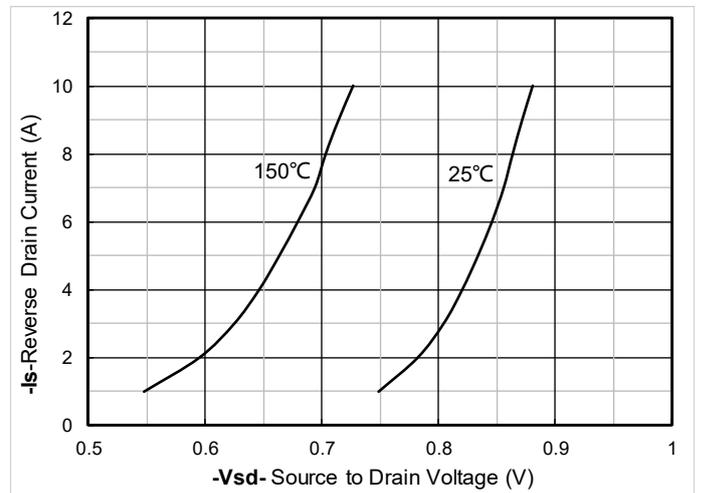


Figure8. Forward characteristics of reverse diode

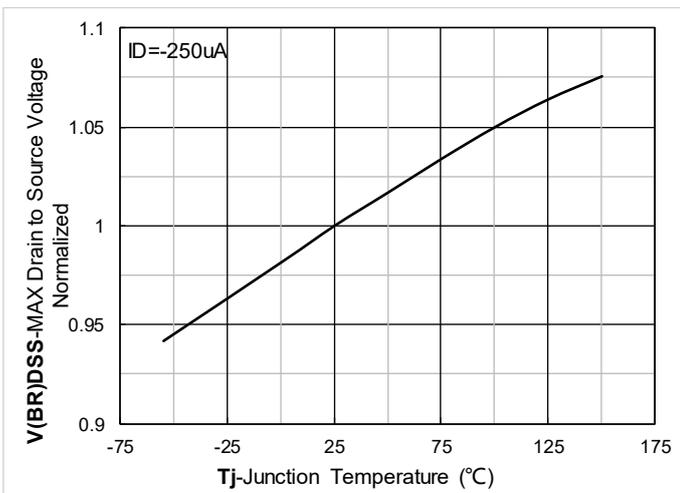


Figure9. Normalized breakdown voltage

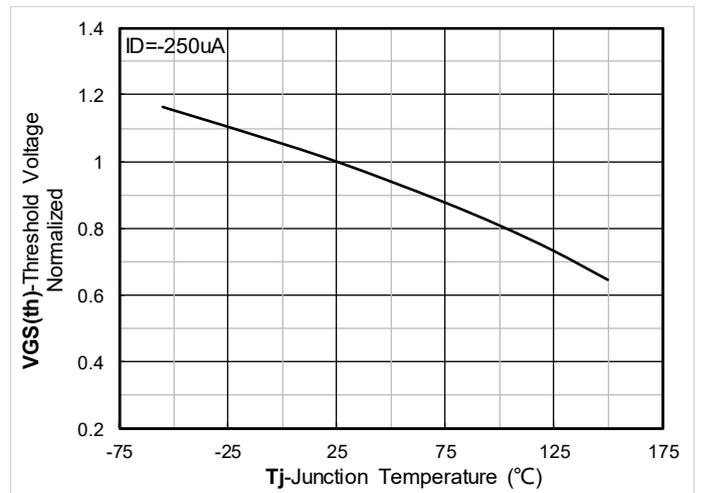


Figure10. Normalized Threshold voltage



# YJG10NP10A

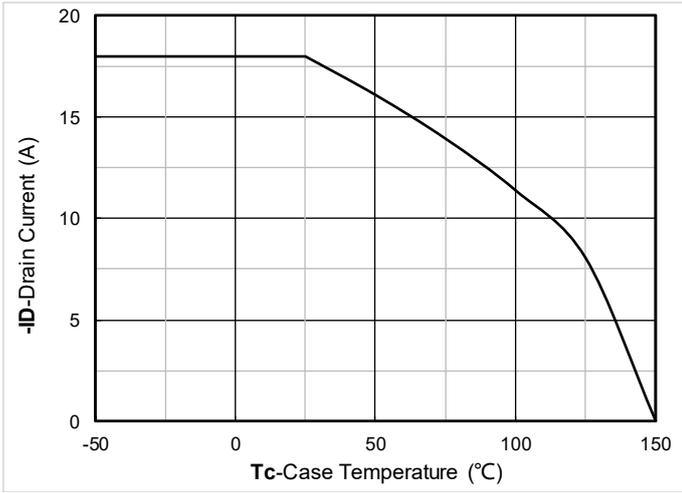


Figure11. Current dissipation

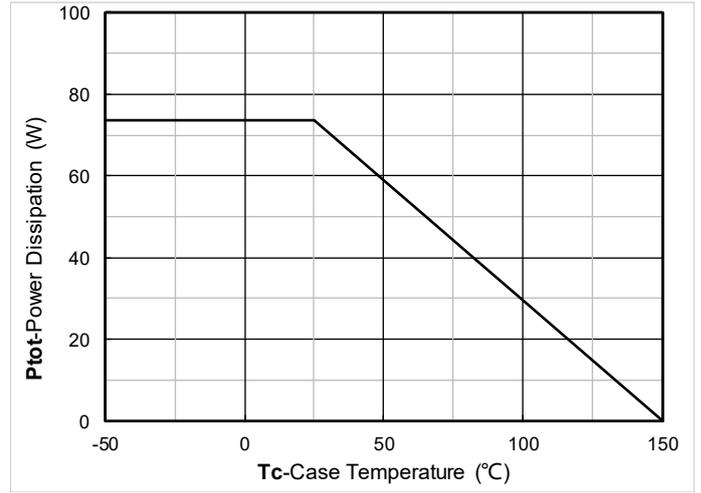


Figure12. Power dissipation

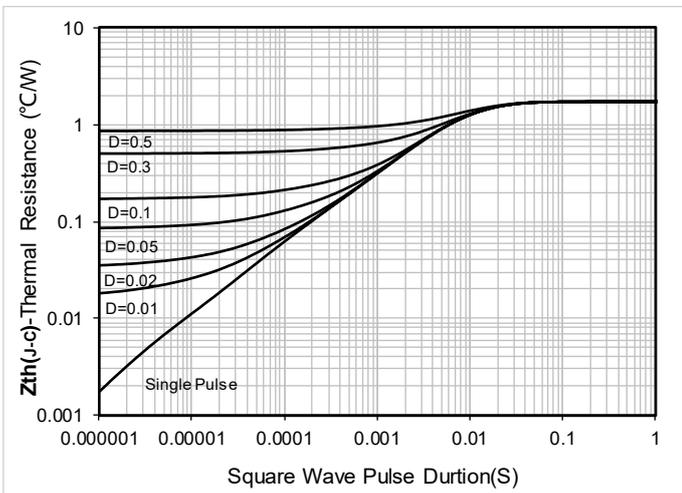


Figure13. Maximum Transient Thermal Impedance

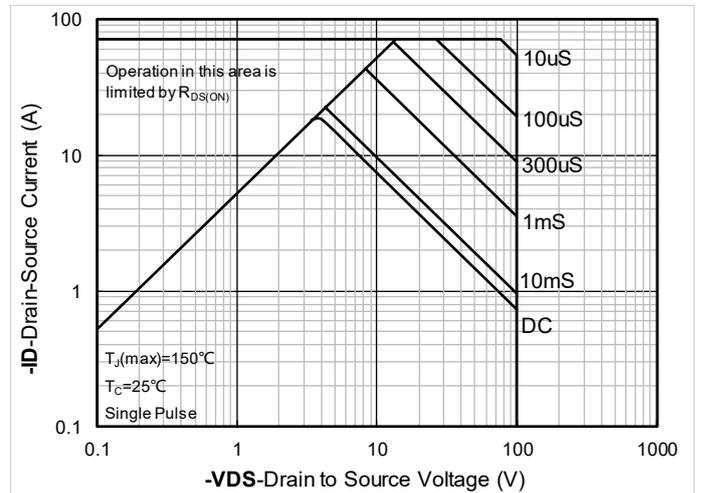
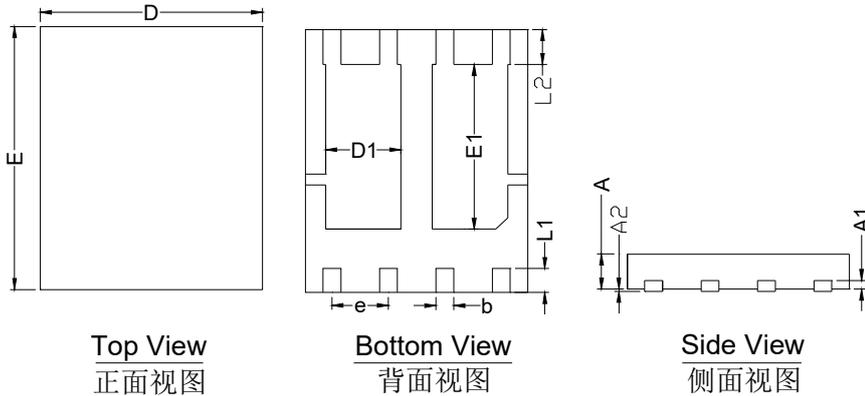


Figure14. Safe Operation Area



# YJG10NP10A

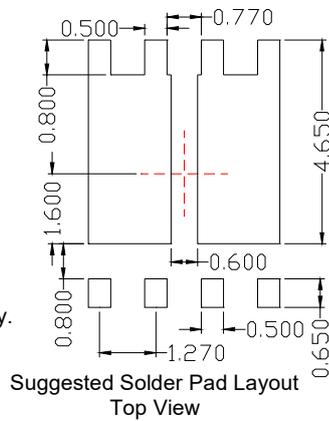
## DFN5060-8L Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	4.90	5.00	5.10
E	5.90	6.00	6.10
A	0.70	0.80	0.90
A1	0.20 BSC		
A2			0.10
D1	1.60	1.70	1.80
E1	3.65	3.75	3.85
L1	0.45	0.55	0.65
L2	0.80 BSC		
b	0.30	0.40	0.50
e	1.27 BSC		

**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.10\text{mm}$ .
3. The pad layout is for reference purposes only.





# YJG10NP10A

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